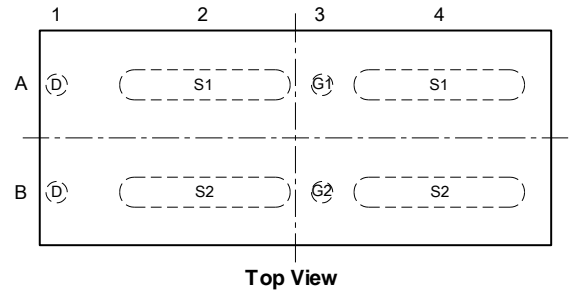
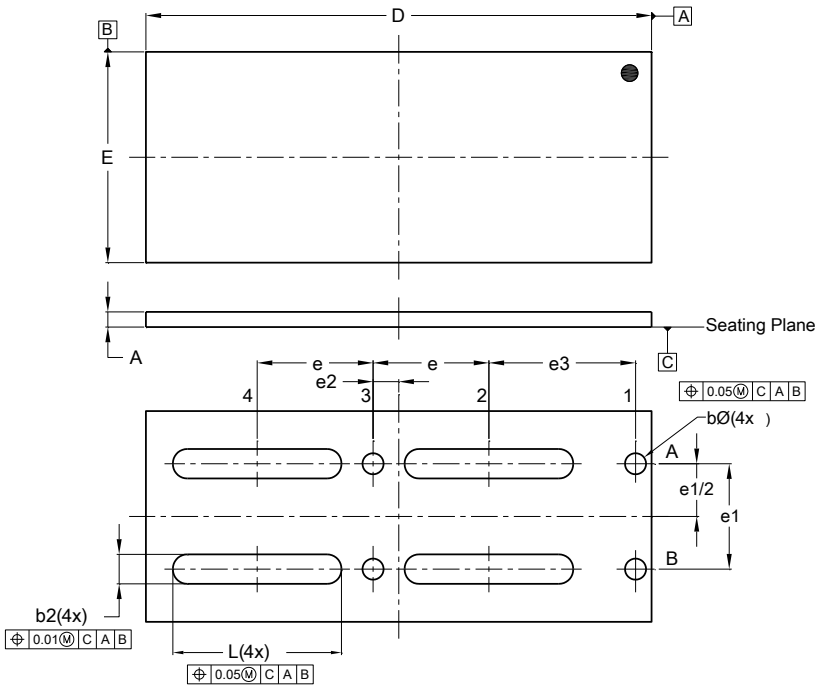


## Package Outline Dimensions

X4-DSN6025-8

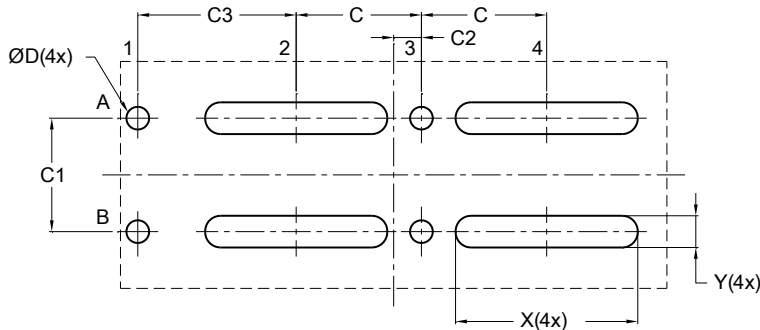


Pin Assignment			
A1	D	B1	D
A2	S1	B2	S2
A3	G1	B3	G2
A4	S1	B4	S2

X4-DSN6025-8			
Dim	Min	Max	Typ
A	0.14	0.22	0.18
b	--	--	0.25
b2	--	--	0.35
D	5.95	6.05	6.00
E	2.45	2.55	2.50
e	1.375 BSC		
e1	1.250 BSC		
e2	0.305 BSC		
e3	1.740 BSC		
L	1.97	2.03	2.00
All Dimensions in mm			

## Suggested Pad Layout

X4-DSN6025-8



Dimensions	Value (in mm)
C	1.375
C1	1.250
C2	0.305
C3	1.740
D	0.250
X	2.000
Y	0.350

### ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.